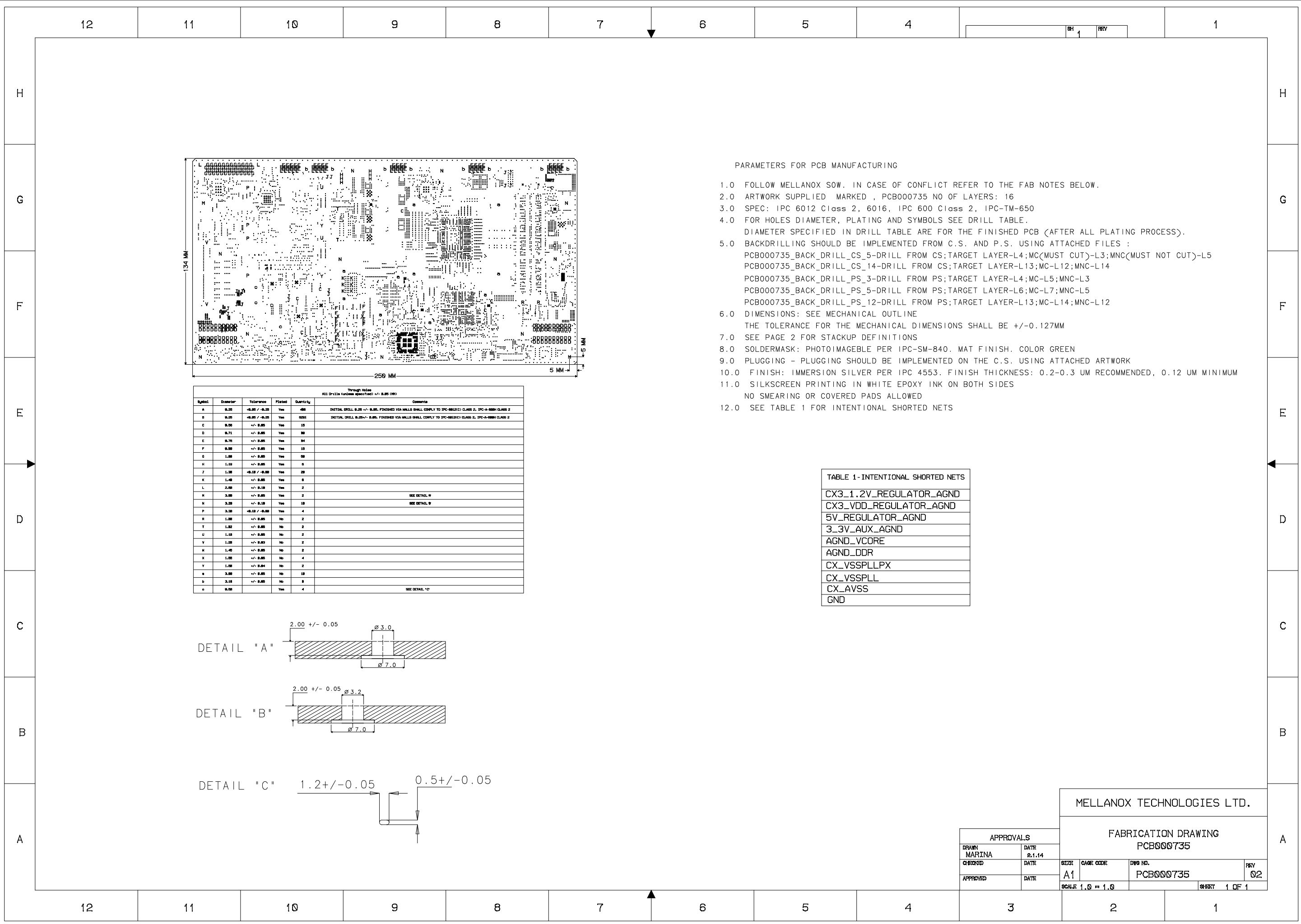




Stack-up and impedance requirements



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Date:	12/12/2013
P/N:	PCB000735
Layers:	16
Total Thickness:	100±10%
Finish:	Immersion silver

Material:	High Tg FR-4
PCB size and PCB units per array	250x134mm, 1 PCB per Panel
Gold finger:	No
Back drill depth/width types on CS:	2
Back drill depth/width types on PS:	3

All dimensions are in mils unless otherwise stated

Layer	Copper parameters				Resin parameters				Impedance parameters							
	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plaiting [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]	Differential pairs parameters					SE signal parameters		
									Imp. [Ω]	Default		Neck-down		Imp.[Ω]	Default Width	Neck-down Width
									Width	Space	Width	Space				
Layer 1 - CS	Signal	0.33	Don't care	Don't care					100±10%	4.75	10.25	3.88	6.12	50±10%	5.63	
Prepreg					3.65	FR4	Don't care	Don't care	90±10%	4.88	5.62					
Layer 2	GND	0.5	0.6	Don't care					85±10%	4.88	4.12					
Core					7.95	FR4	Don't care	Don't care								
Layer 3	Signal	0.5	0.6	Don't care					100±10%	6.3	14	4	5	50±10%	6.5	
Prepreg									95±10%	7	14	4	4.1			
Layer 4	GND	0.5	0.6	Don't care					90±10%	7.5	11	4.6	4			
Core					3	FR4	Don't care	Don't care	85±10%	7.5	7.5	5.1	3.8			
Layer 5	Signal	0.5	0.6	Don't care												
Prepreg					14	FR4	Don't care	Don't care	90±10%	4.1	9	3.4	5	50±10%	3.7	
Layer 6	GND	0.5	0.6	Don't care					85±10%	4.3	6.7	4	5	40±10%	6	
Core					3	FR4	Don't care	Don't care								
Layer 7	Power	1.0	1.2	Don't care												
Prepreg					3	FR4	Don't care	Don't care								
Layer 8	Power	1.0	1.2	Don't care												
Core					3	FR4	Don't care	Don't care								
Layer 9	Power	1.0	1.2	Don't care												
Prepreg					3	FR4	Don't care	Don't care								
Layer 10	Power	1.0	1.2	Don't care												
Core					3	FR4	Don't care	Don't care								
Layer 11	GND	0.5	0.6	Don't care												
Prepreg					14	FR4	Don't care	Don't care								
Layer 12	Signal	0.5	0.6	Don't care												
Core					3	FR4	Don't care	Don't care								
Layer 13	GND	0.5	0.6	Don't care												
Prepreg					7.95	FR4	Don't care	Don't care								
Layer 14	Signal	0.5	0.6	Don't care												
Core					7.95	FR4	Don't care	Don't care								
Layer 15	GND	0.5	0.6	Don't care												
Prepreg					3.65	FR4	Don't care	Don't care								
Layer 16 - PS	Signal	0.33	Don't care	Don't care												

If you have any queries please do not hesitate to contact:
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Or
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Revision		Revision control:	
Date		Description	
X1		11/5/2013	
00		12/12/2013	
01		2/1/2014	
02		8/1/2014	

Notes:	
1	Impedance controlled differential pairs widths are defined with two digits after the decimal points inside the gerbers. Eg 9 mil width is defined as 8.99.
2	The dielectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW designer approval is a must)
3	Trace widths are nominal finished dimensions.